Device Material Content

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Package: 128 TQFP (1.4mm)
Total Device Weight 0.706 Grams

Package Code: TG128
Products: LPTM10 (dual die)

Assembly: ASET
Size (mm): 14 x 14 x 1.4
Lead pitch (mm): 0.4
MSL: 3
Reflow max (ºC): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	0.98%	0.0070						Dual Die package (+Silicon spacer)
			0.46%	0.0031	Silicon chip 1	7440-21-3	44.59%	Die1 Size: 3.52x3.52 mm
			0.21%	0.0014	Silicon chip 2	7440-21-3	20.14%	Spacer Size: 2.15x2.13 mm
			0.31%	0.0021	Silicon chip 3	7440-21-3	30.21%	Die2 Size: 2.65x2.65 mm
Mold Compound	68.20%	0.4815						Mold compound: Sumitomo G631SH (ULA)
			2.73%	0.0193	Epoxy Resin A	-	4.00%	
			2.73%	0.0193	Epoxy Resin B	834893-60-6	4.00%	
			3.41%	0.0241	Phenol Resin	628290-34-6	5.00%	
			0.27%	0.0019	Carbon Black	1333-86-4	0.40%	
			59.06%	0.4170	Silica Fused	60676-86-0	86.60%	
D/A Tape	0.60%	0.0042						Hitachi FH-900 HR-9004 series
			0.09%	0.00063	Epoxy Resin	-	15.00%	
			0.09%	0.00063	Phenol Resin	-	15.00%	
			0.03%	0.00021	SiO2 Filler	99439-28-8	5.00%	
			0.39%	0.00274	(Meta)Acrylic Copolymer	-	65.00%	
Wire	0.24%	0.0017						0.8 mil wire diameter; 1 wire for each package lead
			0.24%	0.00167	Gold (Au)	7440-57-5	99.00%	
			0.00%	0.00002	Palladium (Pd)	7440-05-3	1.00%	
Plating	3.12%	0.0220						Plating is 100% matte Sn (annealed)
			3.12%	0.0220	Tin (Sn)	7440-31-5	100.00%	
Leadframe	26.86%	0.1896						C7025
			25.97%	0.1834	Copper (Cu)	7440-50-8	96.70%	
			0.81%	0.0057	Nickel (Ni)	7440-02-0	3.01%	
			0.05%	0.0003	Silicon (Si)	7440-21-3	0.17%	
			0.01%	0.0001	Magnesium (Mg)	7439-95-4	0.03%	
			0.02%	0.0002	Silver (Ag)	7440-22-4	0.09%	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
Constituent substances and proportions in epoxy materials are before curing.
The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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Br/Cl/Sb

Pb lead-free RoHS

Rev. D